



Sphere Alloy: Sn96.5/Ag3.0/Cu0.5 (SAC305)

Sizes (mm):	(0.100mm~0.450mm) ± 0.010mm
(inches):	0.004" ~ 0.018"
Melting Point:	217~218°C
Specific Gravity:	7.40
Working Temp.	255~260 °C

Composition Analysis (Weight %)

Item	Composition			Impurity							
	<i>Sn</i>	<i>Ag</i>	<i>Cu</i>	<i>Pb</i>	<i>Sb</i>	<i>Zn</i>	<i>Fe</i>	<i>As</i>	<i>Bi</i>	<i>Cd</i>	<i>Al</i>
IPC JSTD -006B	BAL	3.0 ±0.2	0.5 ±0.1	<0.05	<0.05	<0.001	<0.02	<0.03	<0.03	<0.002	<0.001

Product Type and Weight

Type	BGA Solder Ball		
Dimen.	(0.100mm~0.450mm)± 0.010mm		
	sphericity deviation < 1.5%		Illuminance ≥ 270 Lux
Package	Package Material	Package Grade	Label
	PP.Bottle	Anti Static	Part No. Description, Date

Storage / Handling and Shelf Life

Shelf life is 1 year from date of purchase. Refrigeration is not recommended and does not extend shelf life. The container should remain unopened and not agitated. Normal fluctuations in room temperature will not affect shelf life. Avoid contamination of spheres from contact with foreign objects such as fingers or moisture.

Reflow Profile / Placement

Follow the reflow profile as recommended by the flux or solder paste manufacturer. This product is used in world wide semiconductor packaging processes, which is most commonly applied in automatic ball placement machines.

Health

This product, during handling or use, may be hazardous to health or the environment. Read the Material Safety Data Sheet and warning label before using this product.